## **Data Sheet**







The iLED-FMB1.5-COB-GA features cutting-edge COB (Chip-on Board) technology offering affordable performance for professional requirements.

## **Features**

## High Reliability

The flip chip technology ensures stable and reliable performance, with an extremely low failure rate.

## Excellent Flatness

Ultra thin die cast aluminum alloy shell, high precision, substrate adopts large module design.

## Ultra Clear Picture Quality

Approaching the true horizon infinitely; Vividly restore natural colors.

## • Ultra High Contrast

The real contrast ratio is as high as 10000:1, achieving better ink consistency.

#### Soft Picture

Surface light source design, caring for the eyes; The product can reduce moire lines effectively.

## Super Protection

Waterproof, dustproof, anti-static, moisture-proof, mildew-proof, and anti-bump for maximum durability.

# **√** Technical Specifications

LED MODULE	
Model Number	iLED-FMB1.5-COB-GA
Pixel Pitch Exhibited(mm)	1.56
LED Type	COB(Flip Chip)
Module Size(WxH)	300 x 168.75
Pixel Per Module(dots)	192 x 108
Panel Size(mm)	600 x 337.5 x 34
Pixel Per Panel(dots)	384 x 216
Material	Die casting Aluminum
Weight(kg/panel)	3.5
Brightness(nits)	600 ~ 800
Gray scale (bit)	14
Refresh rate (Hz)	3840
Color Temperature(K)	3200~9300
Viewing angle(H)	170°
Viewing angle(V)	160°
Power Max.(W/m²)	300
Operating Temperature(°C)	-10~+40
Module IP Rating (Front)	IP65
Installation/Maintenance	Front

